

**AMENDMENTS****IN THE SPECIFICATION**

Please replace the title with the following title:

**CHIP PACKAGE WITH DIE AND SUBSTRATE**

Please insert the following paragraph prior to the section labeled, BACKGROUND OF THE INVENTION.

This application is related to application No. 10/054,001, filed on Jan. 19, 2002, now Pat. No. 6,673,698; and related to application No. 10/690,350, filed on Oct. 21, 2003, now pending; and related to application No. 10/996,535, filed on Nov. 24, 2004, now pending; and related to application No. 10/996,537, filed on Nov. 24, 2004, now pending; and related to application No. 10/055,498, filed on Jan. 22, 2002, now Pat. No. 6,800,941; and related to application No. 10/454,972, filed on Jun. 4, 2003, now pending; and related to application No. 10/055,560, filed on Jan. 22, 2002, now pending; and related to application No. 10/638,018, filed on Aug. 8, 2003, now pending; and related to application No. 10/977,289, filed on Oct. 28, 2004, now pending; and related to application No. 10/174,462, filed on Jun. 17, 2002, now Pat. No. 6,746,898; and related to application No. 10/755,042, filed on Jan. 9, 2004, now pending; and related to application No. 10/055,499 filed on Jan. 22, 2002, now pending; and related to application No.

10/728,150 filed on Dec. 3, 2003, now pending; and related to application No. 10/794,472 filed on Mar. 5, 2004, now pending, all assigned to a common assignee.